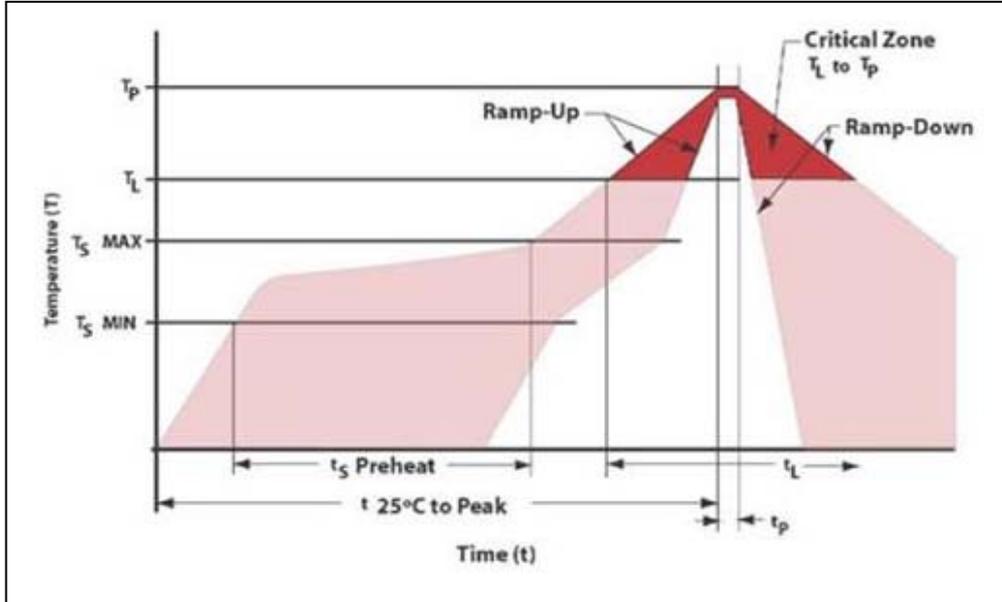


Reflow Temperature Profile (MEMS Oscillators)

The solder reflow profile shown in following figure is IPC/JEDEC J-STD-020 compliant and applies to all KDS MEMS packages; QFN, SOT23-5, 2.0x1.2 SMD, and WLCSP.

■ Reflow Temperature Profile

(Available for lead free soldering)



■ High Temperature Infrared/Convection Reflow Conditions IPC/JEDEC J-STD-020

IPC/JEDEC Standard	IPC/JEDEC J-STD-020
Moisture Sensitivity Level	Level 1
TS MAX to TL (Ramp-up Rate)	3°C/second Maximum
Preheat	
- Temperature Minimum (TS MIN)	+150°C
- Temperature Typical (TS TYP)	+175°C
- Temperature Maximum (TS MAX)	+200°C
- Time (tS)	60 - 180 Seconds
Ramp-up Rate (TL to TP)	3°C/second Maximum
Time Maintained Above:	
- Temperature (TL)	+217°C
- Time (TL)	60 - 150 Seconds
Peak Temperature (TP)	+260°C Maximum
Target Peak Temperature (TP Target)	+255°C
Time within 5°C of actual peak (tP)	20 - 40 seconds
Max. Number of Reflow Cycles	3
Ramp-down Rate	6°C/second Maximum
Time 25°C to Peak Temperature (t)	8 minutes Maximum

Refer to datasheet for details of reflow profile specifications.